



Product Change Notice (PCN)

Changed Product: PHANES-F Series Wide Temperature MLC SDHC & SDXC Memory Card 3.0	Doc. No.: PCN_099-XXSDH-PFITMA-1V0
	Date: 2016 / 04 / 14
Change Description and the reasons: Toshiba MLC flash IC manufacturing process has been upgraded from A19nm to 15nm. As Toshiba MLC A19nm flash IC chips announced EOL in 2015, in order to adapt to the MLC flash trend, APRO will now transit all Toshiba MLC A19nm products to Toshiba MLC 15nm products for longer lifetime and more stable availability.	
If you have any questions, please contact with your APRO Sales Account Manager.	
Key Dates: Last Buy: 2016 / 07 / 31 Last Shipment: 2015 / 10 / 31	

Part Number List (Max. 20 codes)			
Operating Temp.	Capacity	Before Change	After Change
Standard Temp. 0°C~70°C			
Operating Temp.	Capacity	Before Change	After Change
Wide Temp. -40°C~85°C	4GB	WPSDH004G-PFITMA ^{*1}	WPSDH004G-PFITMB
	8GB	WPSDH008G-PFITMA	WPSDH008G-PFITMB
	16GB	WPSDH016G-PFITMA	WPSDH016G-PFITMB
	32GB	WPSDH032G-PFITMA	WPSDH032G-PFITMB
	64GB	WPSDX064G-PFITMA	WPSDX064G-PFITMB

Remarks:

- (R) stands for Rugged Metal CF frame
- TMA vs TMB:
 TMA stands for Toshiba MLC A19nm flash IC
 TMB stands for Toshiba MLC 15nm flash IC

Production Management	Engineering Department	Product Management	Sales Department
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